



SOT618-13(DD)

HVQFN40, plastic thermal enhanced very thin quad flat package; no leads, wettable flanks; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

11 December 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package type industry code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-11-2018
Manufacturer package code	98ASA01025D

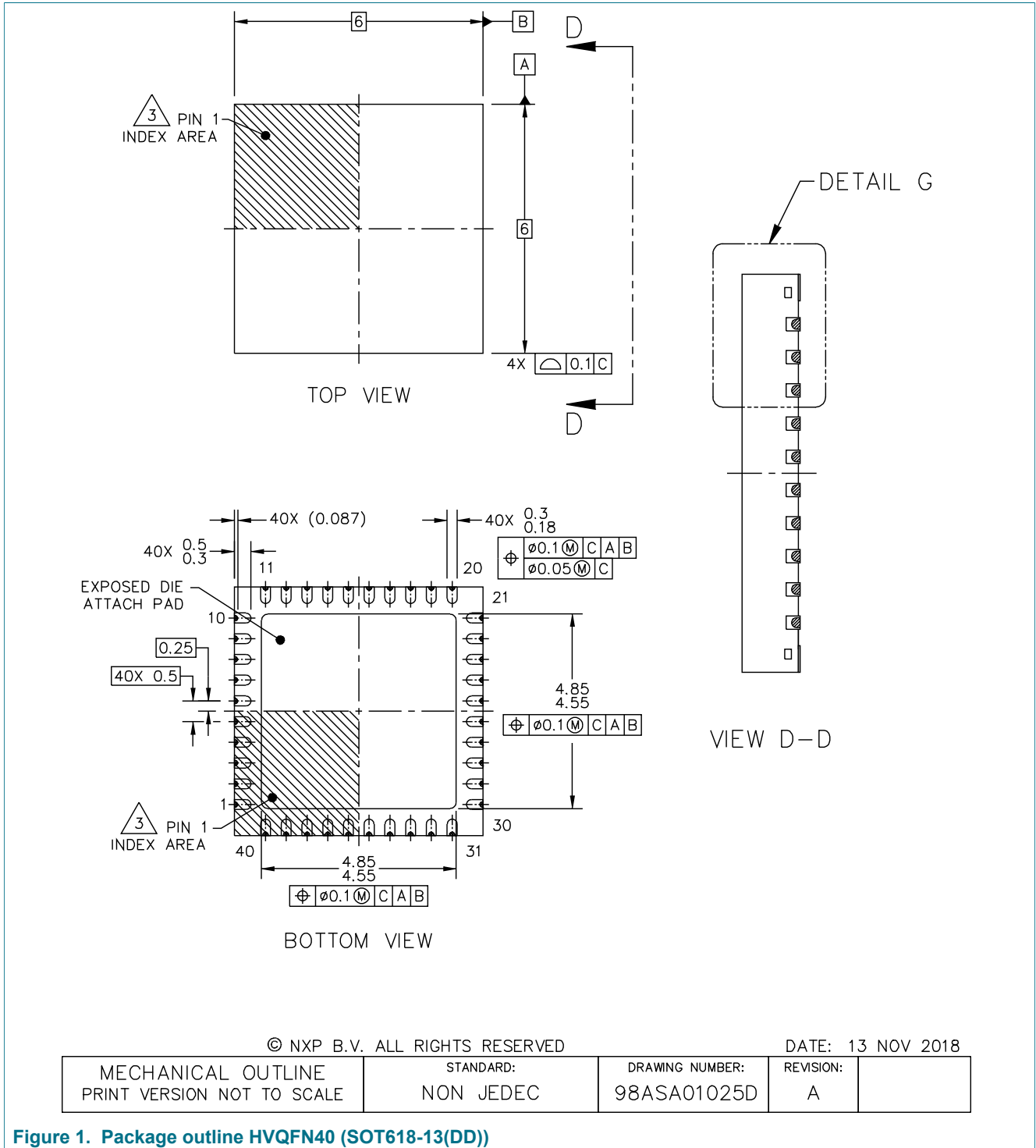
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	6	-	mm
seated height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	



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2 Package outline



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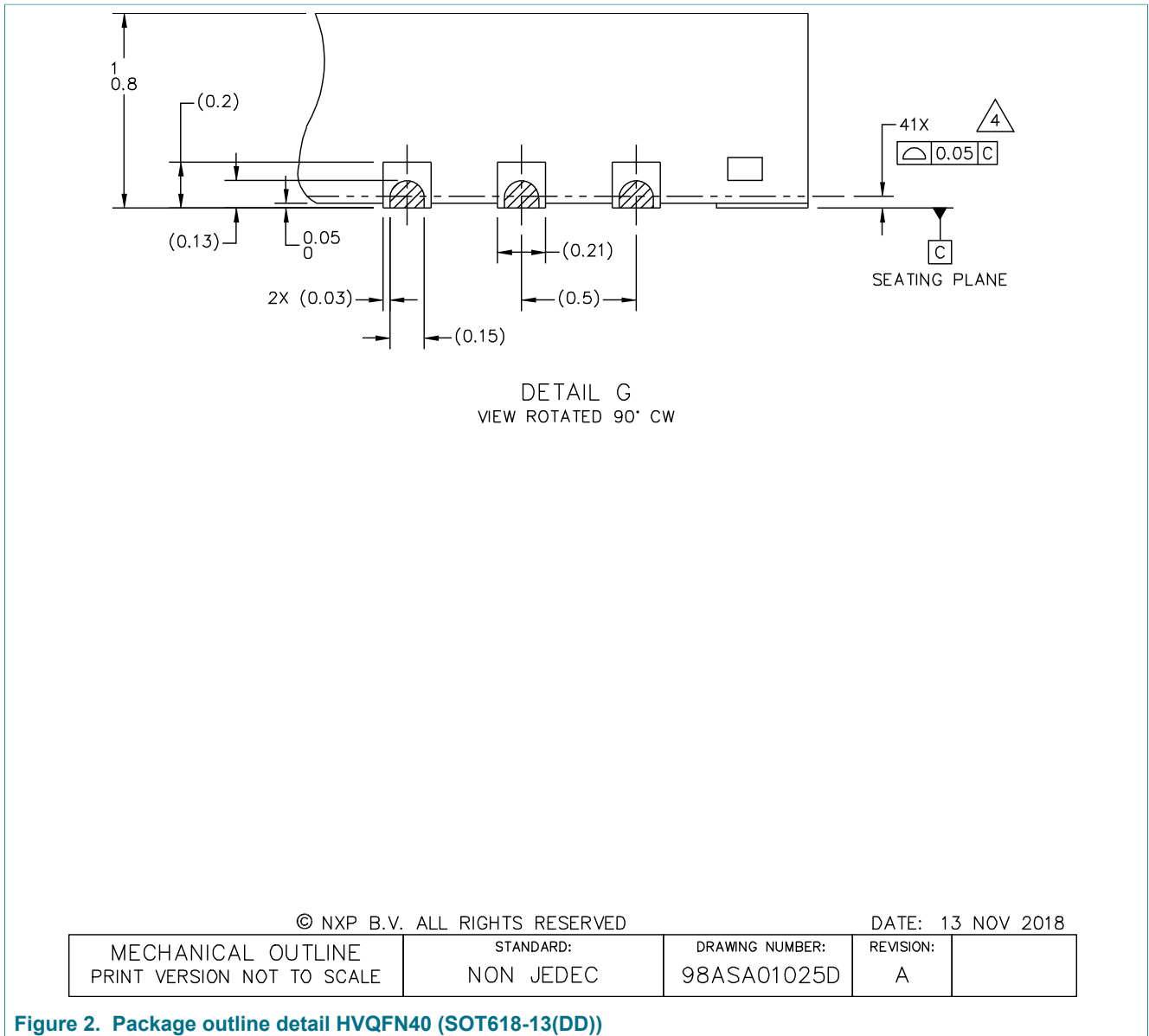


Figure 2. Package outline detail HVQFN40 (SOT618-13(DD))

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3 Soldering

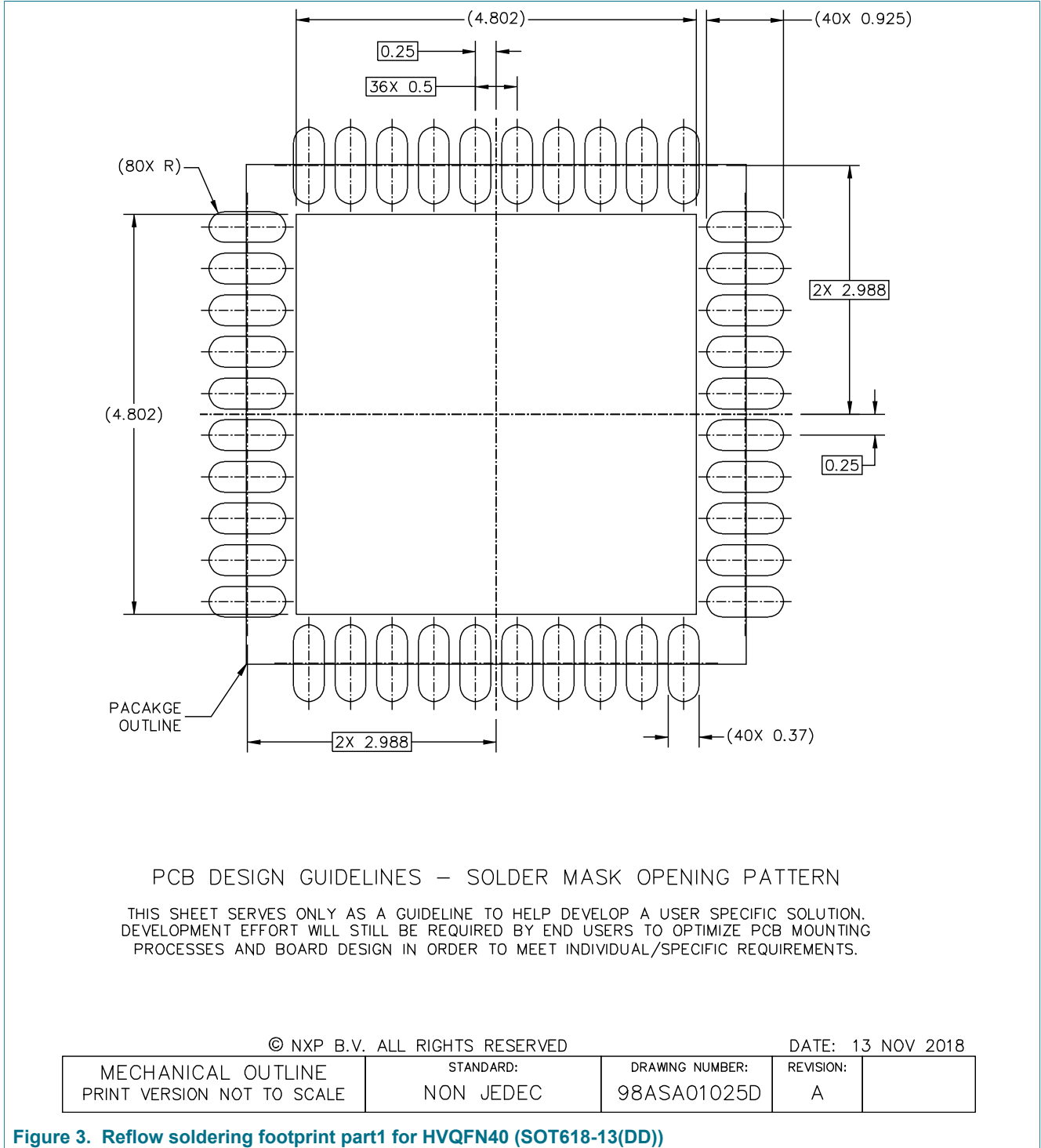


Figure 3. Reflow soldering footprint part1 for HVQFN40 (SOT618-13(DD))

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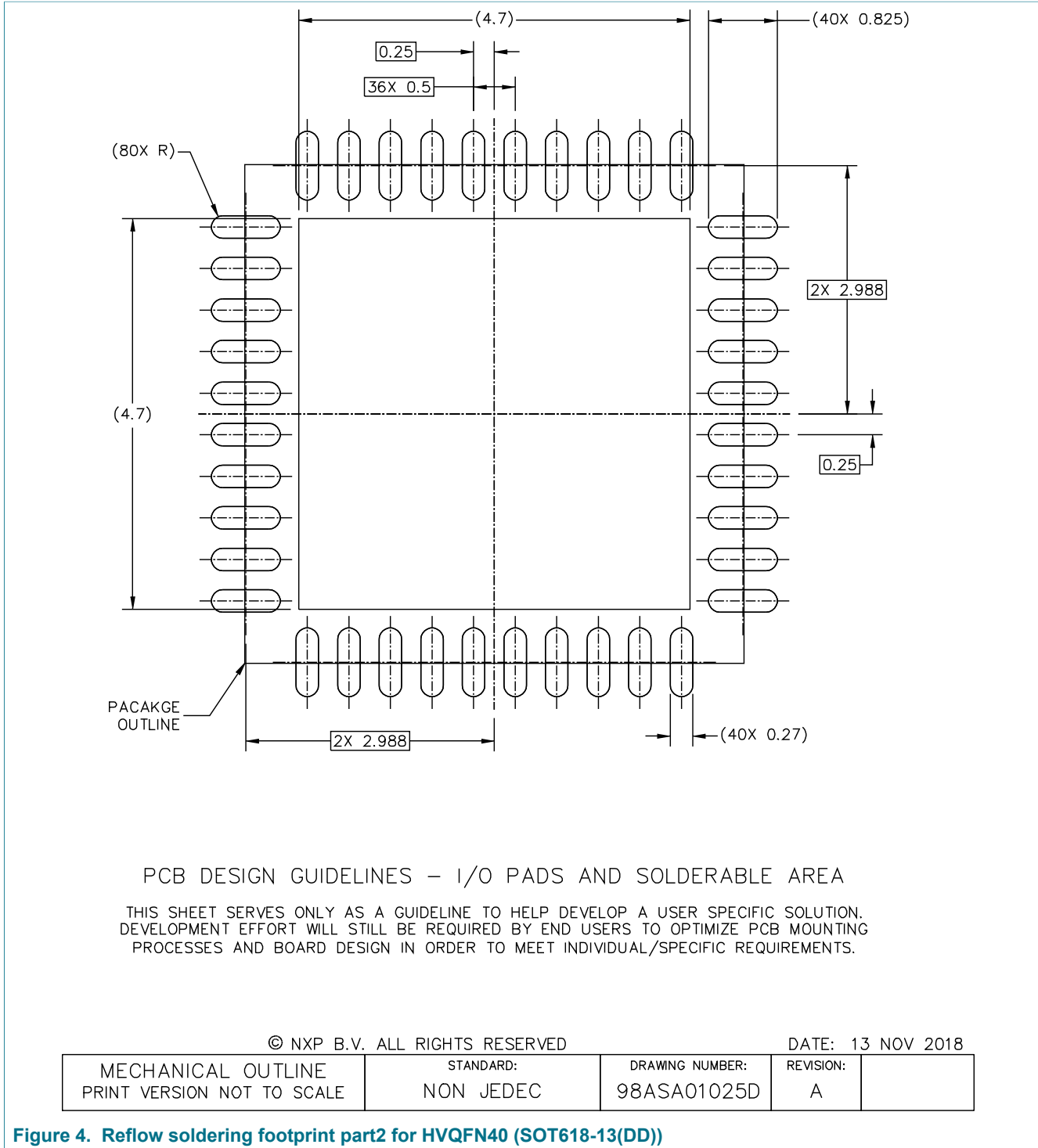
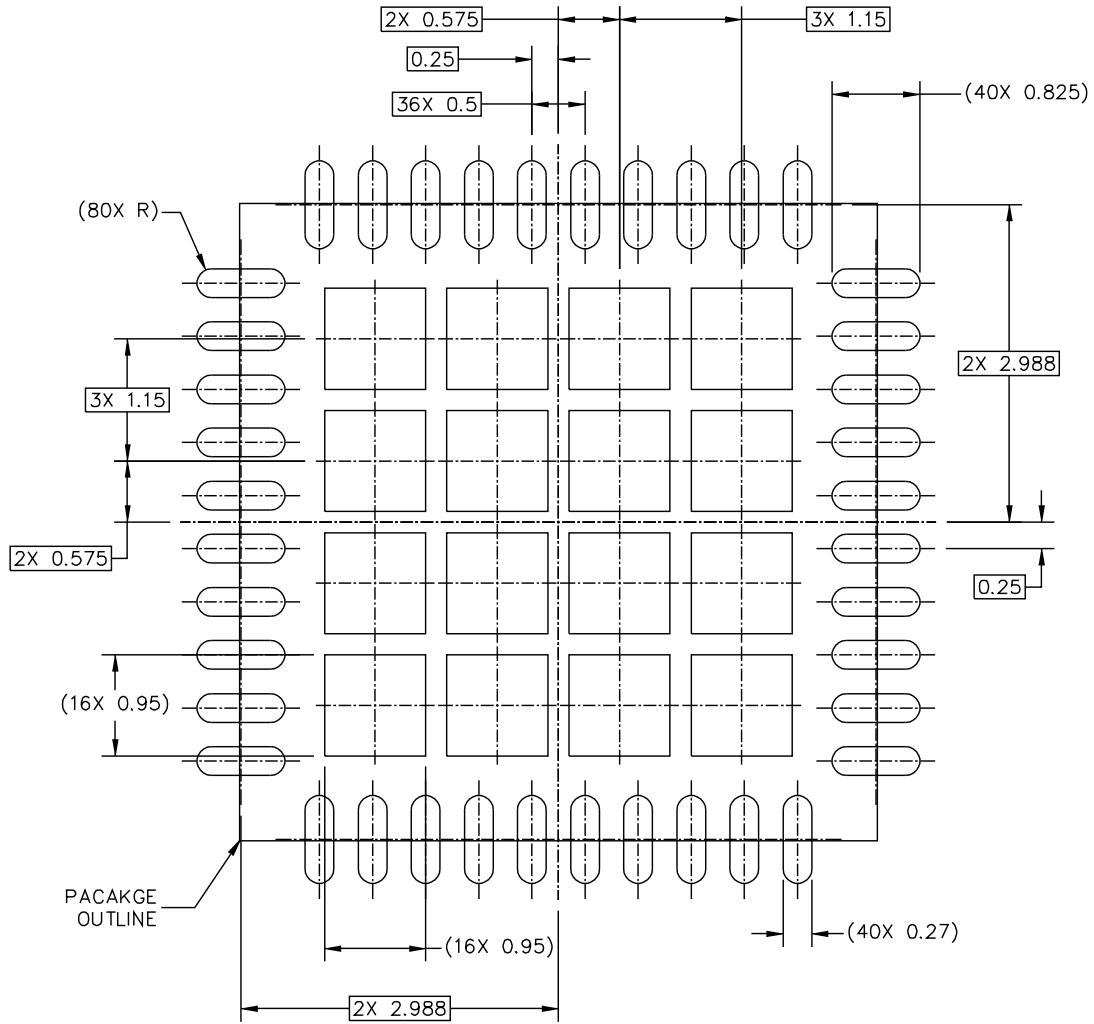


Figure 4. Reflow soldering footprint part2 for HVQFN40 (SOT618-13(DD))

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 13 NOV 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01025D	REVISION: A	
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Figure 5. Reflow soldering footprint part3 for HVQFN40 (SOT618-13(DD))

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.25 MM.

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Figure 6. Package outline note HVQFN40 (SOT618-13(DD))

4 Legal information

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